RELIABILITY REPORT

FOR

MAX6730UTxDx

PLASTIC ENCAPSULATED DEVICES

August 23, 2006,

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Quality Assurance
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Conclusion

The MAX6730 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX6730 single voltage microprocessor (µP) supervisor features a watchdog timer and manual reset capability. The MAX6730 offers factory-set reset thresholds for monitoring voltages from +0.9V to +5V and an adjustable reset input for monitoring voltages down to +0.63V. The combination of these features significantly improves system reliability and accuracy when compared to separate ICs or discrete components.

The active-low reset output asserts and remains asserted for the reset timeout period after all the monitored voltages exceed their respective thresholds. Multiple factoryset reset threshold combinations reduce the number of external components required. The MAX6730 monitors a single fixed voltage. The device is offered with six minimum reset timeout periods ranging from 1.1ms to 1120ms.

The MAX6730 features a watchdog timer with an independent watchdog output. The watchdog timer prevents system lockup during code execution errors. A watchdog startup delay of 54s after reset asserts allows system initialization during power-up. The watchdog operates in normal mode with a 1.68s delay after initialization. The MAX6730 provides an active-low, open-drain watchdog output.

Other features include a manual reset input and open-drain reset output. The MAX6730 is offered in a tiny SOT23-6 package. The device is fully specified over the extended -40°C to +85°C temperature range.

B. Absolute Maximum Ratings

Item	Rating
VCC1, VCC2, RSTIN, MR, WDI to GND	-0.3V to +6V
RST, WDO to GND (open drain)	-0.3V to +6V
RST, WDO to GND (push-pull)	-0.3V to (VCC1 + 0.3V)
Input Current/Output Current (all pins)	20mA
Continuous Power Dissipation (TA = +70°C)	
6-Pin SOT23-6 (derate 8.7mW/°C above +70°C)	696mW
8-Pin SOT23-8 (derate 8.9mW/°C above +70°C)	714mW
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

II. Manufacturing Information

A. Description/Function:	Single Voltage µP Supervisory Circuits with Independent Watchdog Output
B. Process:	B8 (Standard 0.8 micron silicon gate CMOS)
C. Number of Device Transistors:	1,073
D. Fabrication Location:	California or Texas, USA
E. Assembly Location:	Malaysia, Philippines or Thailand
F. Date of Initial Production:	December, 2002

III. Packaging Information

A. Package Type:	**6-Pin SOT23**
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate or 100% Matte Tin
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-9000-0393
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C:	Level 1

IV. Die Information

A. Dimensions:	32 x 57 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Managing Director of QA**)**

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 133 \times 2}$$

(Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 8.27 \times 10^{-9}$

λ = 8.27 F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Attached Burn-In Schematic (Spec. # 06-5953) shows the static Burn-In circuit. Maxim performs failure analysis on any lot that exceeds this reliability control level. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1N**). Current monitor data for the B8/S8 Process results in a FIT rate of 0.17 @ 25°C and 2.92 @ 55°C (eV = 0.8, UCL = 60%).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The MS69Y-2 die type has been found to have all pins able to withstand a transient pulse of ±1500V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX6730UTxDx

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		133	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	SOT	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

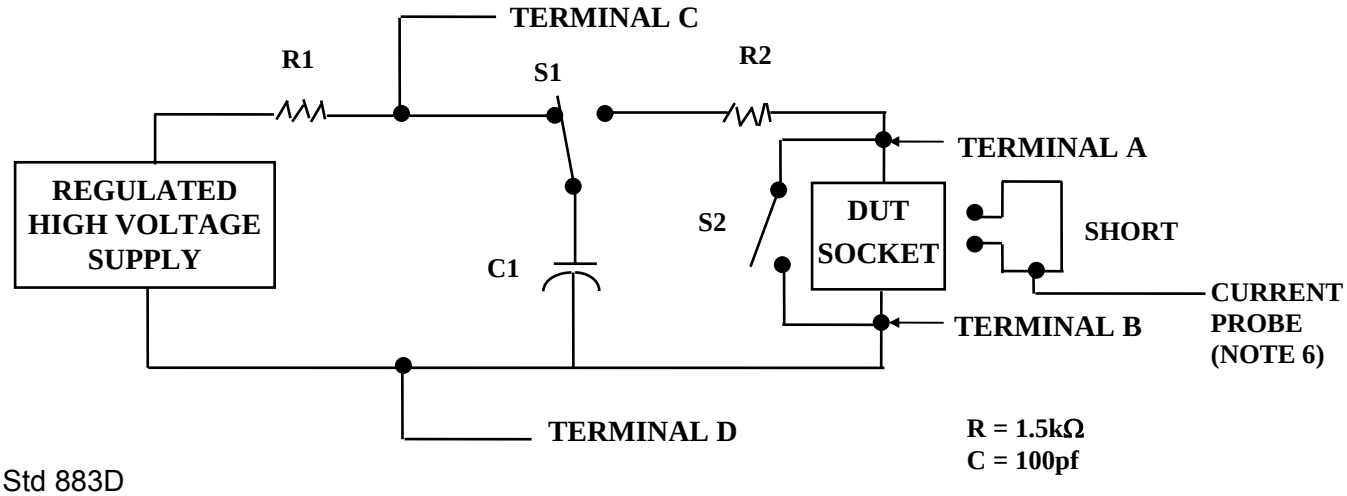
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

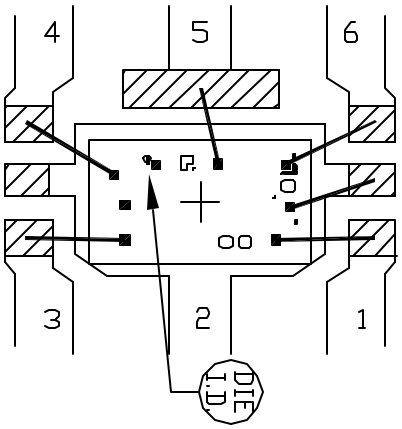
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



Mil Std 883D
Method 3015.7
Notice 8

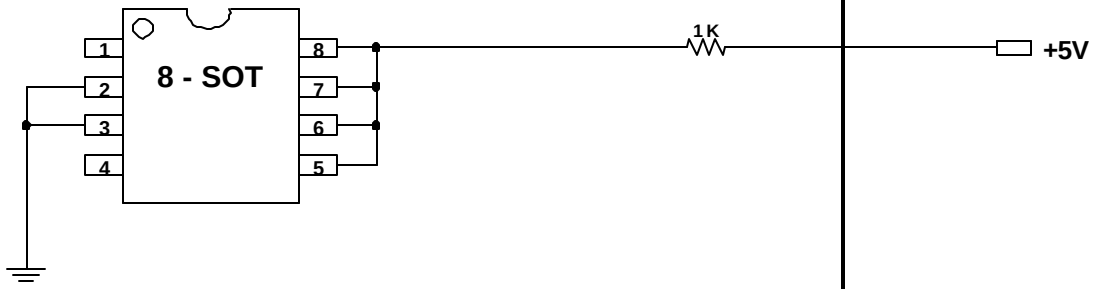


NOTE: CAVITY DOWN

PKG. CODE: U6-1		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 64x39	PKG.			BOND DIAGRAM #: 05-9000-0393	REV: B
	DESIGN				

ONCE PER SOCKET

ONCE PER BOARD



DEVICES: MAX 6725/6726/6727/6728/6729/6734/6735

MAX. EXPECTED CURRENT = 100mA

NOTES: